

SP4203 0.5 pF, 10A bidirectional discrete TVS diodes







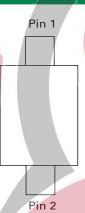




Description

The SP4203 integrates low capacitance diodes to provide electronic equipment protection from destructive electrostatic discharges (ESDs). These robust TVSs can withstand repetitive contact or air ESD discharge events at ± 30 kV levels without suffering any performance degradation. This exceeds the ESD contact and air discharge test requirements of IEC 61000-4-2. Additionally, the TVS can withstand an 8/20 surge current event as defined in IEC 61000-4-5 2nd edition up to 10A and still provide low voltage clamping levels.

Pinout



Features

- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, 10A (8/20 as defined in IEC 61000-4-5 2nd edition)
- Low capacitance of 0.5pF $(@V_{R}=0V)$
- Low leakage current
- Small SOD323 package fits 0805 footprints
- AEC-Q101 qualified
- Halogen free, lead free and RoHS compliant
- Moisture Sensitivity Level (MSL -1)

Functional Block Diagram



Applications

- xDSL Interfaces
- RS-232
- RS-485
- Power Ports
- Security Equipment
- Instrumentation
- Medical Equipment
- Computers and Peripherals

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

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TVS Diode Arrays (SPA® Diodes)

Low Capacitance ESD Protection - SP4203

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I _{PP}	Peak Current (t _p =8/20µs)	10	А
T _{OP}	Operating Temperature	-40 to 125	°C
T _{STOR}	Storage Temperature	-55 to 150	°C

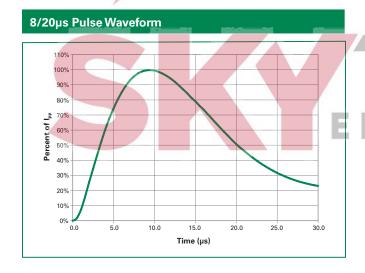
Notes:

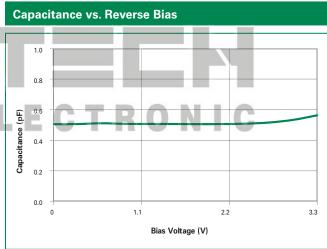
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Electrical Characteristi	cs (T _{OP} =25°	c)				
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Reverse Standoff Voltage	V _{RWM}	I _R =1µA			3.3	V
Breakdown Voltage	V _{BR}	I _R =1mA	5.5	6.6		V
Reverse Leakage Current	I _{LEAK}	V _R =3.3V			0.1	μΑ
Clamp Voltage ¹	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	I _{pp} =1A, t _p =8/20μs		7.5	10	V
	V _C	$I_{pp} = 10A, t_p = 8/20 \mu s$		16.5	20	V
Dynamic Resistance ²	R _{DYN}	TLP, t _p =100ns, I/O to I/O		0.54		Ω
ESD Withstand Voltage ¹	IE IE	IEC 61000-4-2 (Contact Discharge)	±30			kV
	V _{ESD}	IEC 61000-4-2 (Air Discharge)	±30			kV
Diode Capacitance ¹	C _{1/0-1/0}	Reverse Bias=0V, f=1MHz		0.5	0.9	pF

Notes:

^{2.}Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window t1=70ns to t2= 90ns



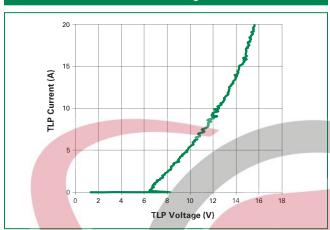


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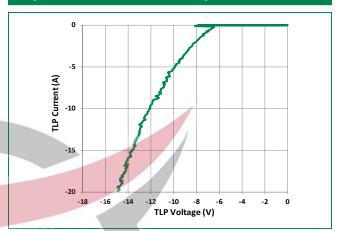
¹ Parameter is guaranteed by design and/or component characterization.



Positive Transmission Line Pulsing (TLP) Plot

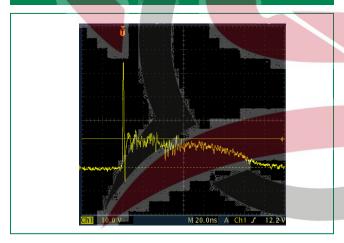


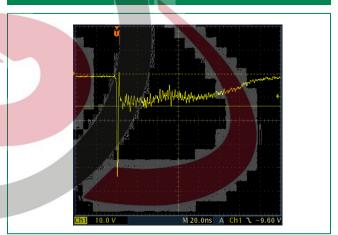
Negative Transmission Line Pulsing (TLP) Plot



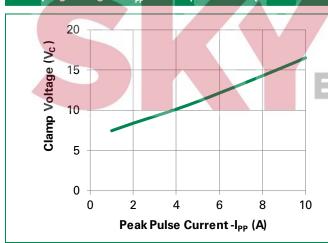
IEC 61000-4-2 +8kV Contact ESD Clamping Voltage







Clamping voltage vs. I for 8/20µs waveshape



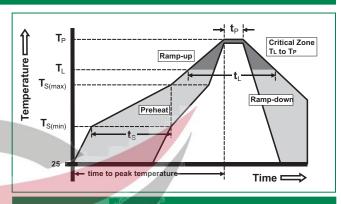
TECTRONIC

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Soldering Parameters

Reflow Condition		Pb – Free assembly	
Pre Heat	-Temperature Min (T _{s(min)})	150°C	
	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 – 180 secs	
Average ramp up rate (Liquidus) Temp (T _L) to peak		3°C/second max	
T _{S(max)} to T _L - Ramp-up Rate		3°C/second max	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
	-Temperature (t _L)	60 – 150 seconds	
Peak Temperature (T _P)		260 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		20 - 40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes Max.	
Do not exceed		260°C	

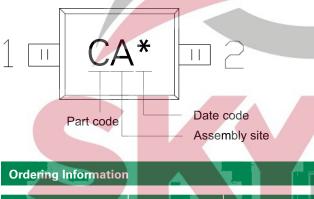


Product Characteristics

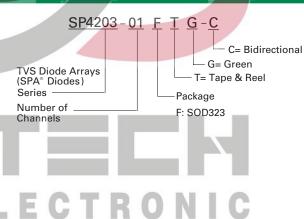
Lead Plating	Matte Tin	
Lead Material	Alloy 42	
Lead Coplanarity	0.004 inches(0.102mm)	
Substrate Material	Silicon	
Body Material	Molded Compound	
Flammability	UL Recognized compound meeting flammability rating V-0	

Part Marking System

SP4203-01FTG-C



Part Numbering System



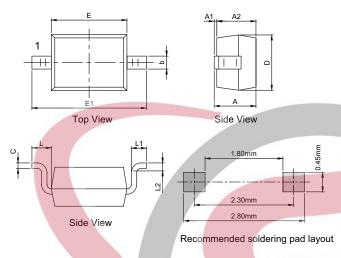
Part Number Package Min. Order Oty.

SOD323

3000



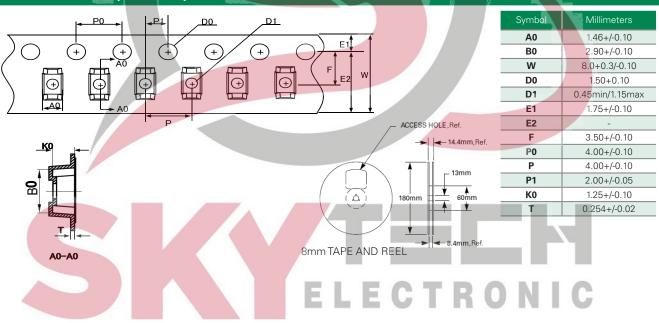
Package Dimensions -SOD323



Symbol	SOD323				
	Millimeters		Inches		
	Min	Max	Min	Max	
Α	-	1.00	-	0.039	
A1	0.00	0.10	0.000	0.004	
A2	0.80	0.90	0.031	0.035	
b	0.25	0.35	0.010	0.014	
С	0.08	0.15	0.003	0.006	
D	1.20	1.40	0.047	0.055	
E	1.60	1.90	0.063	0.075	
E1	2.50	2.70	0.098	0.106	
L	0.475 REF		0.019 REF		
L1	0.25	0.40	0.010	0.016	
L2	0.20 BSC		0.008 BSC		

Drawing#: F03-A

Embossed Carrier Tape & Reel Specification — SOD32



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